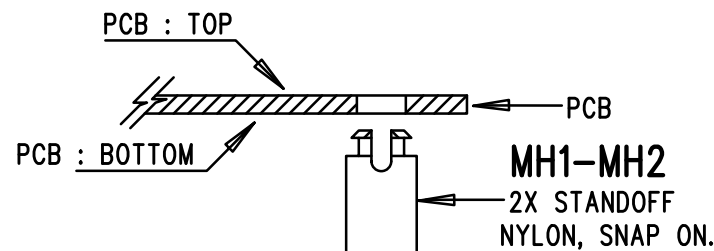


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	1ST PROTOTYPE	MARK T.	05-28-14

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 2 STANDOFFS AS SHOWN BELOW:



APPROVALS

PCB DES.	KIM T.
APP ENG.	MARK T.

SCALE = NONE



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TITLE: TOP ASSEMBLY DRAWING
24-BIT PRECISION DIGITAL
TEMPERATURE MEASUREMENT SYSTEM

SIZE N/A	IC NO. LTC2983CLX DEMO CIRCUIT 2209A	REV. 1
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FILENAME: DC2209A-1.PCB

SHT 1 OF 2